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 TPS76733
 TPS76750
 TPS76725
 TPS76033
 SHEET 10, 11, 12, 13

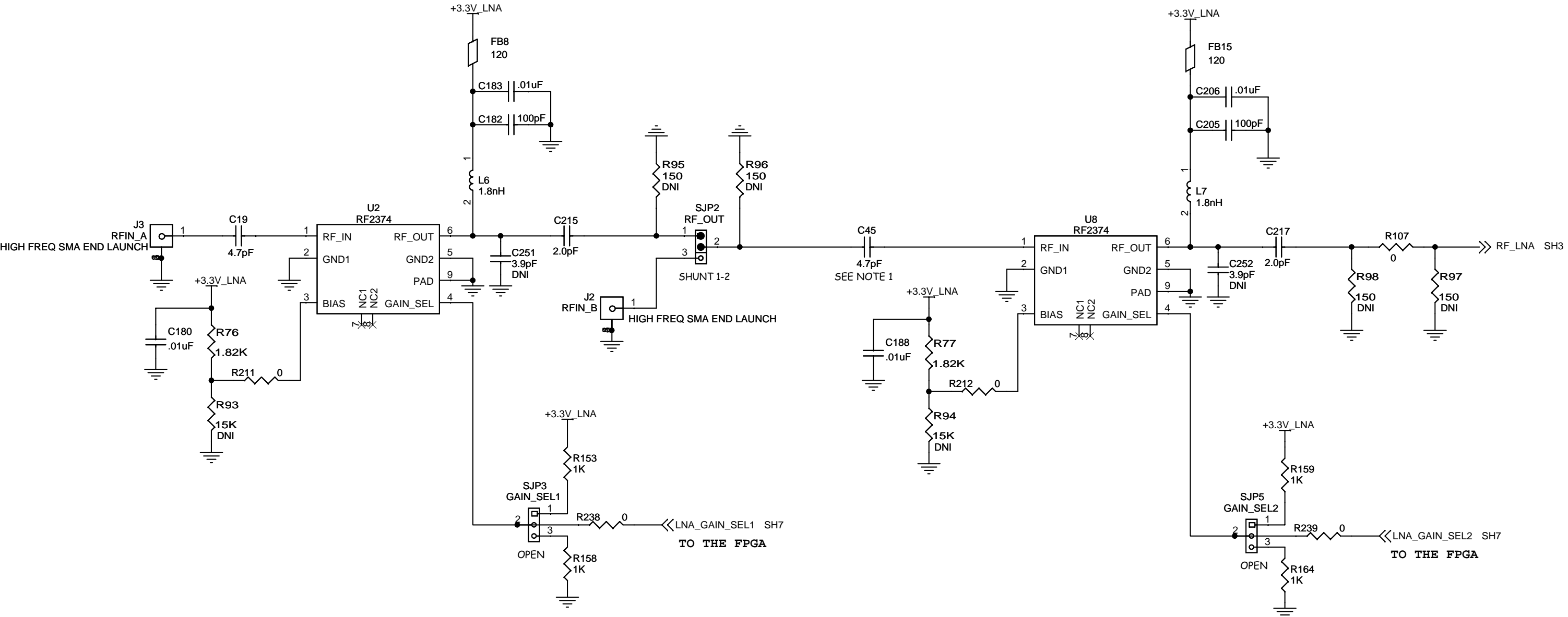
NOTE: DNI = DO NOT INSTALL



Engineer: J. SETON		Title TSW6011 EVM	
Size B	Document Number Cover	Rev C	
Date: Thursday, August 12, 2010	Sheet 1 of 14		

NOTES:
 1. 8 PLACES SHEETS 2 & 3

	CAP	RF BALUN
Mfg_Kit_A	169 10pF	MURATA LDB211G9005C
Mfg_Kit_B	265 4.7pF	MURATA LDB212G4005C Use Johanson part instead
Mfg_Kit_C	365 3.9pF	JOHANSON 3600BL14M050E
Mfg_Kit_D	167 10pF	MURATA LDB211G8005C
Mfg_Kit_E	900M 22pF	MURATA LDB21897M05C



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Size B	Document Number TRF3711	Rev C
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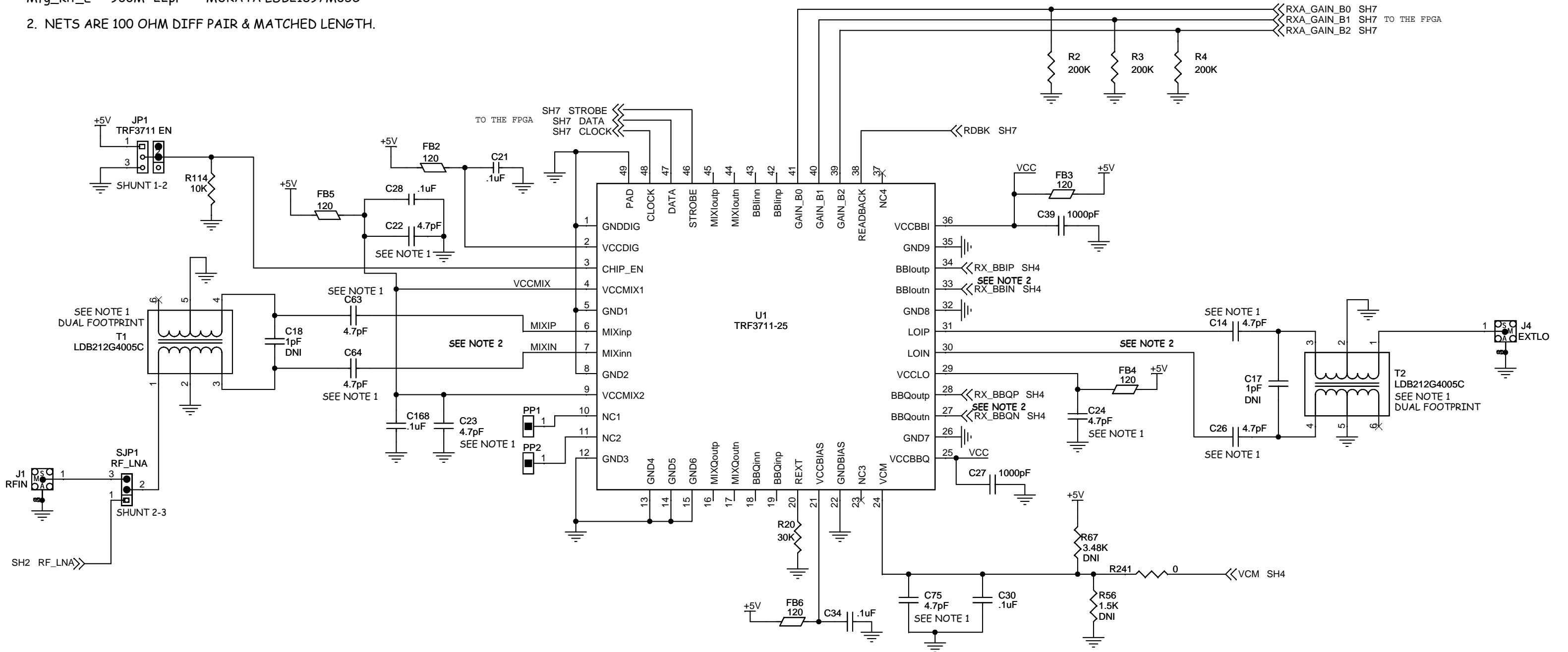
Date: Thursday, August 12, 2010 Sheet 2 of 14

NOTES:

1. 8 PLACES - SHEETS 2 & 3

		CAP	RF BALUN
Mfg_Kit_A	169	10pF	MURATA LDB211G9005C
Mfg_Kit_B	265	4.7pF	MURATA LDB212G4005C Use Johanson part instead
Mfg_Kit_C	365	3.9pF	JOHANSON 3600BL14M050E
Mfg_Kit_D	167	10pF	MURATA LDB211G8005C
Mfg_Kit_E	900M	22pF	MURATA LDB21897M05C

2. NETS ARE 100 OHM DIFF PAIR & MATCHED LENGTH.

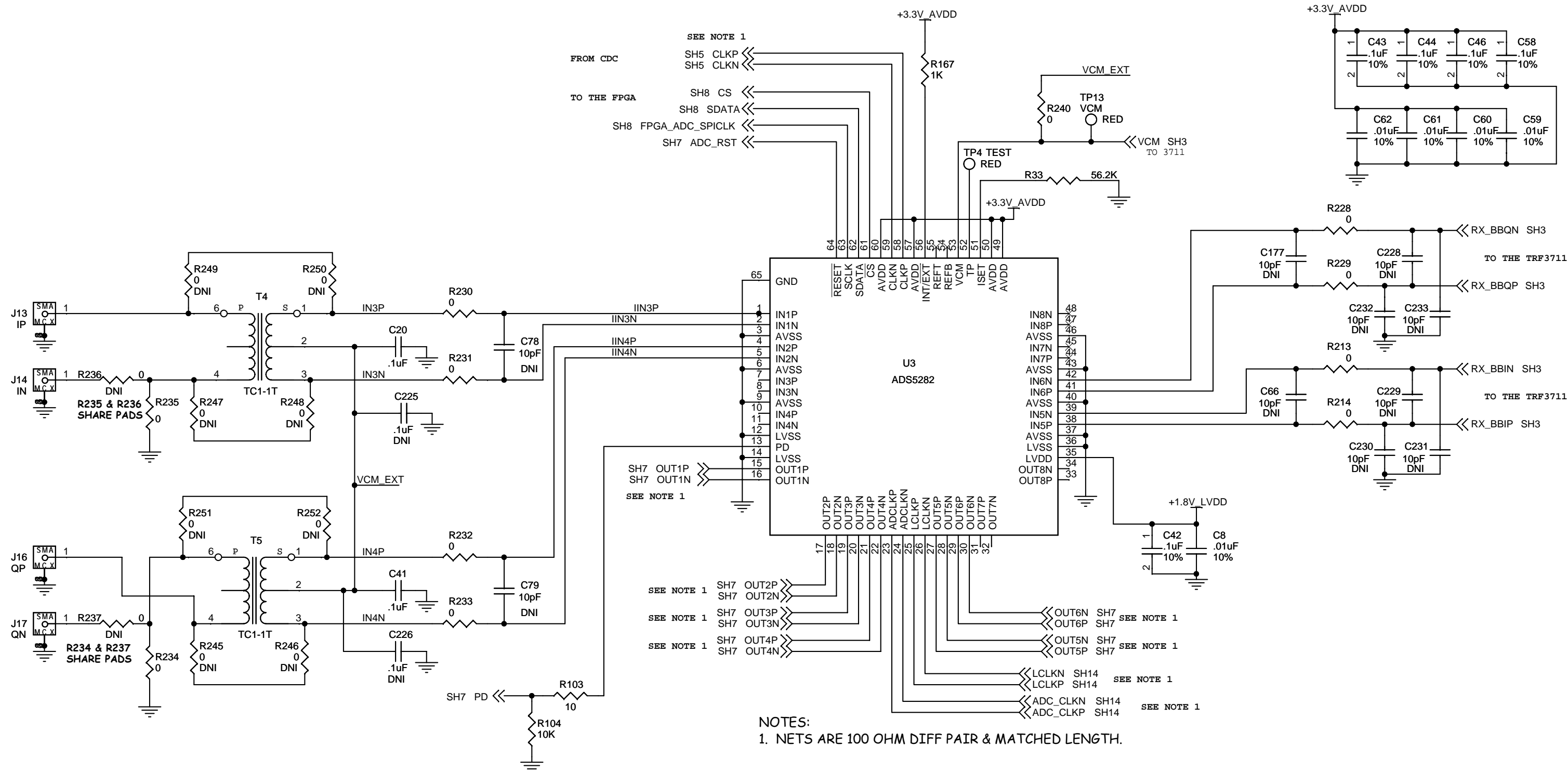


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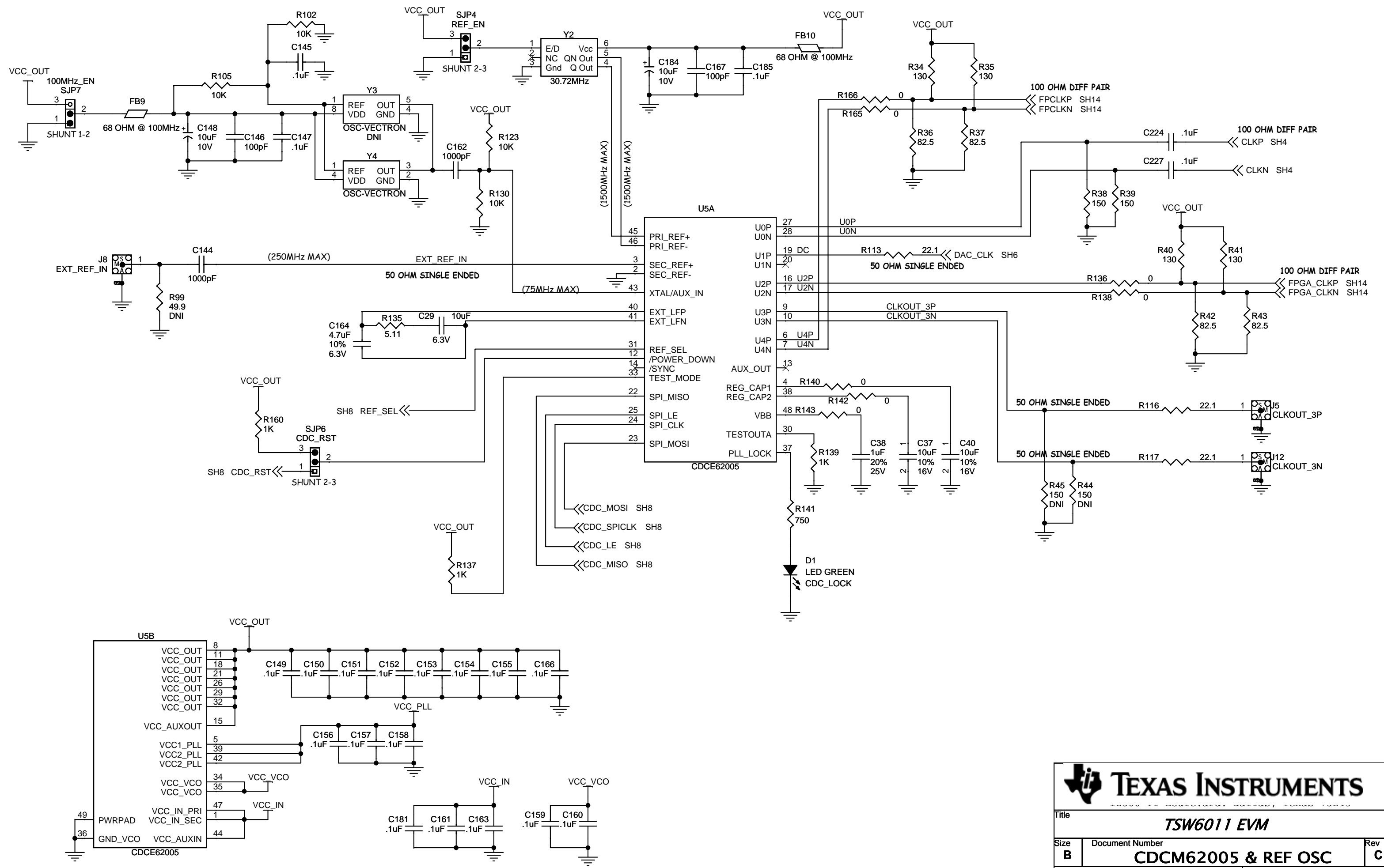
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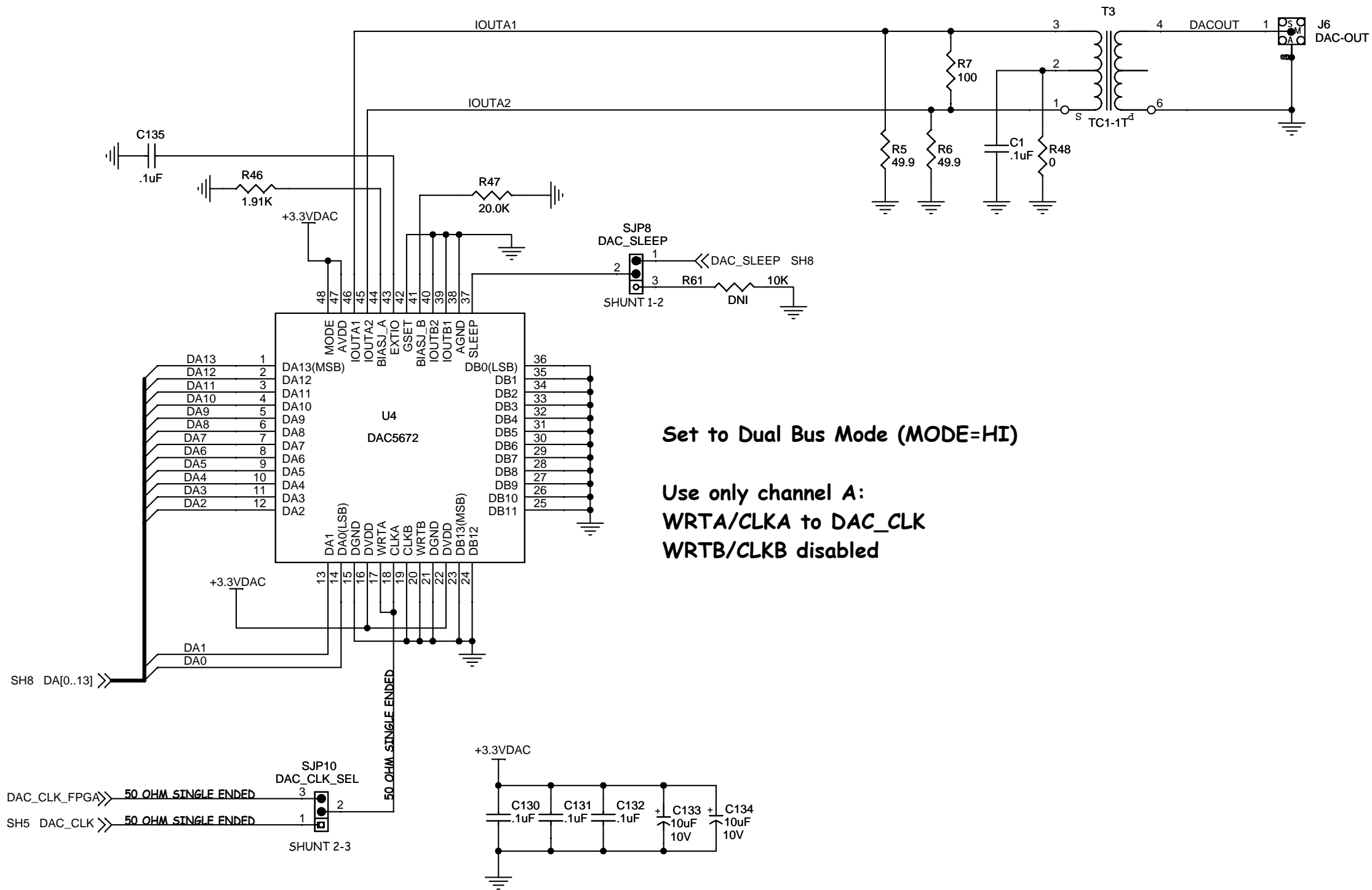
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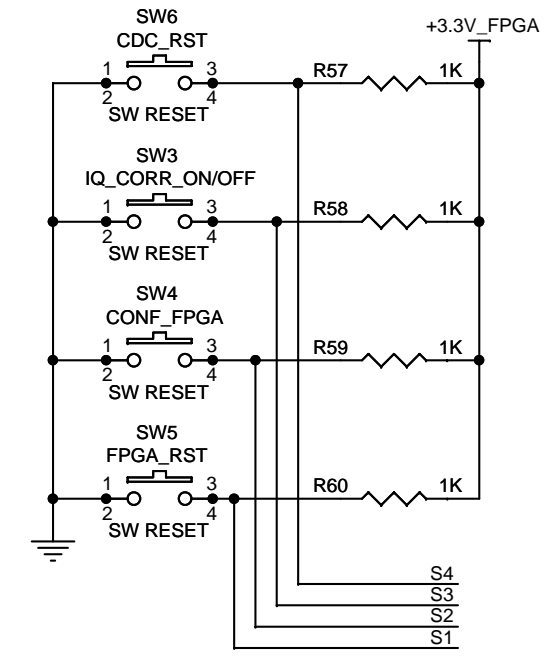
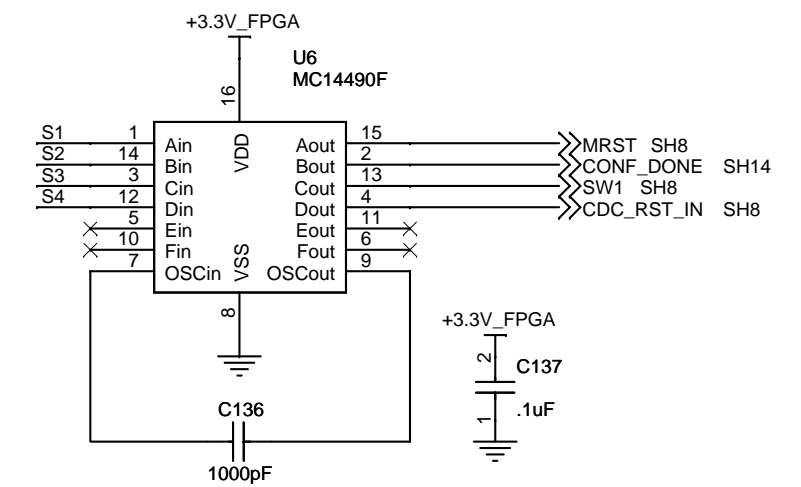
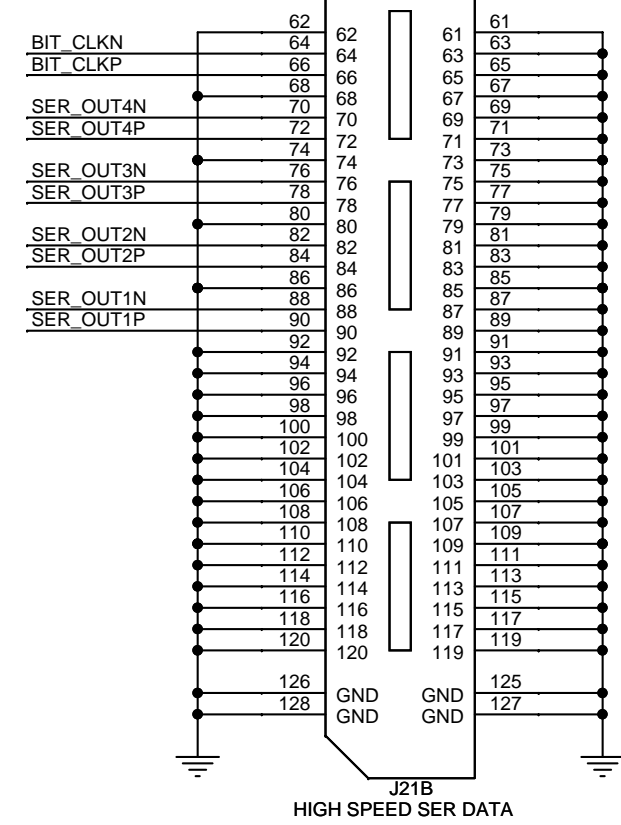
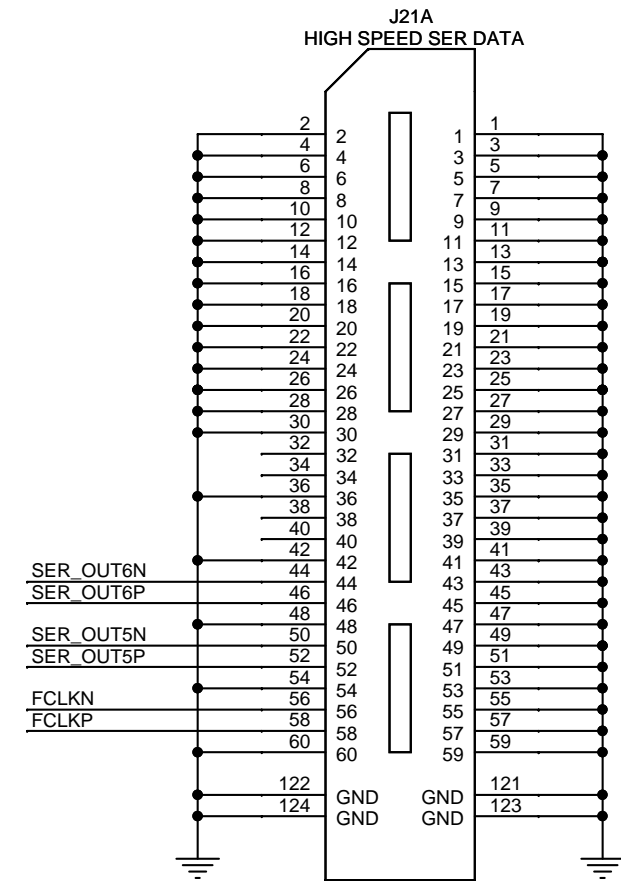
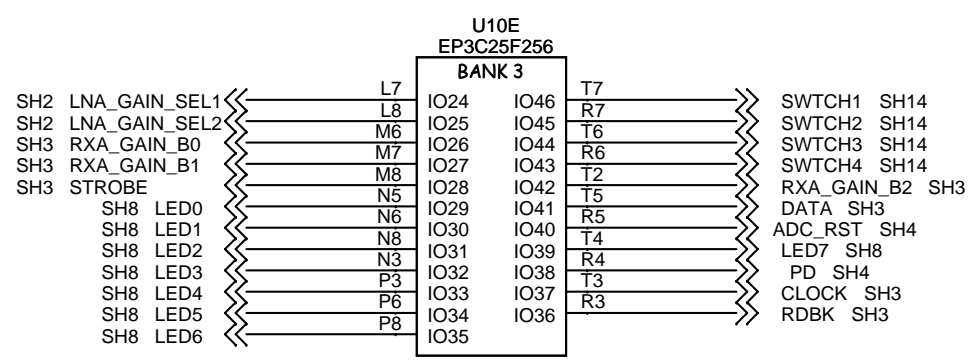
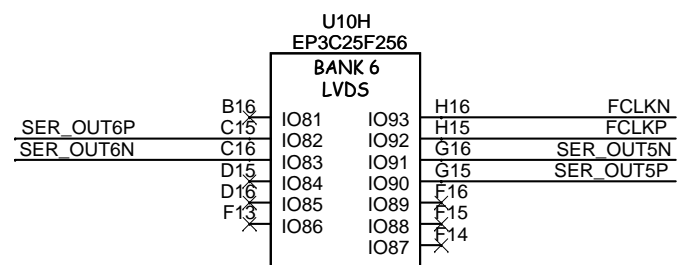
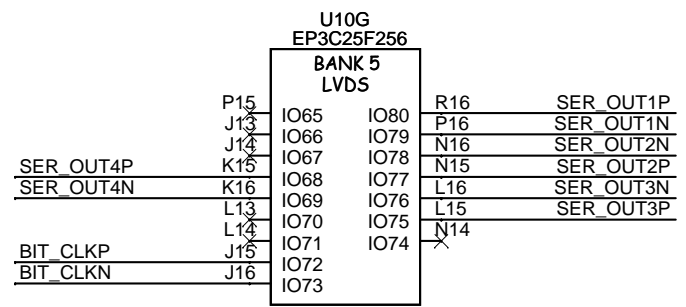
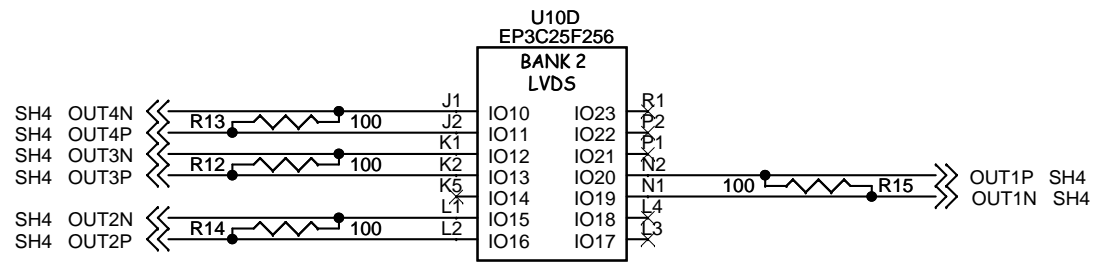
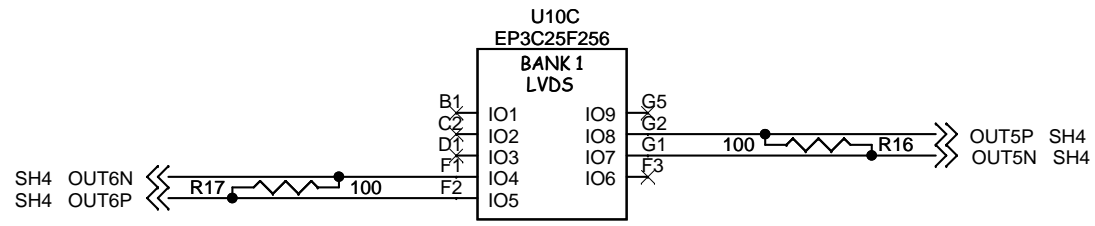
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Size **B** Document Number **ADS5282** Rev **C**

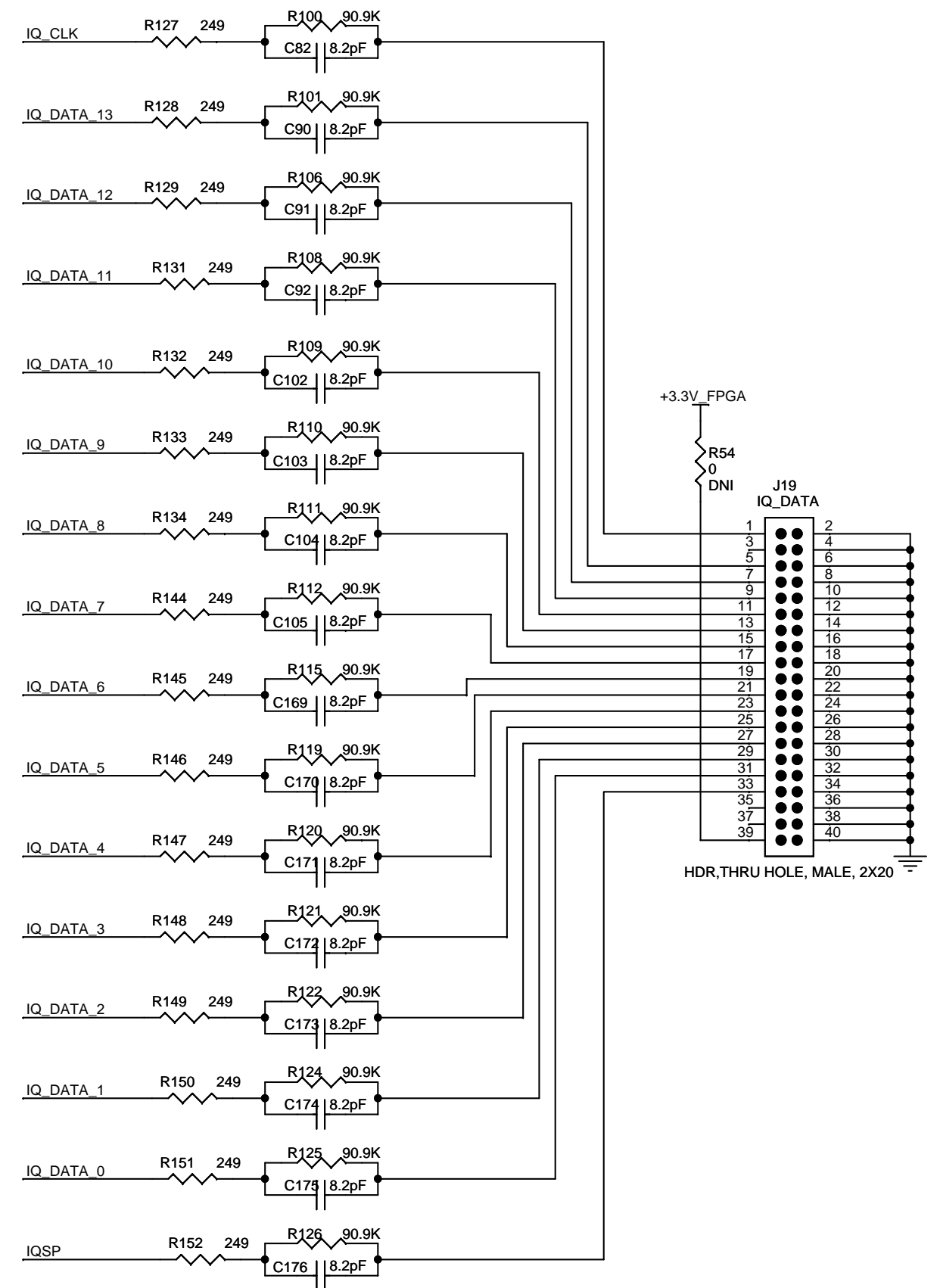
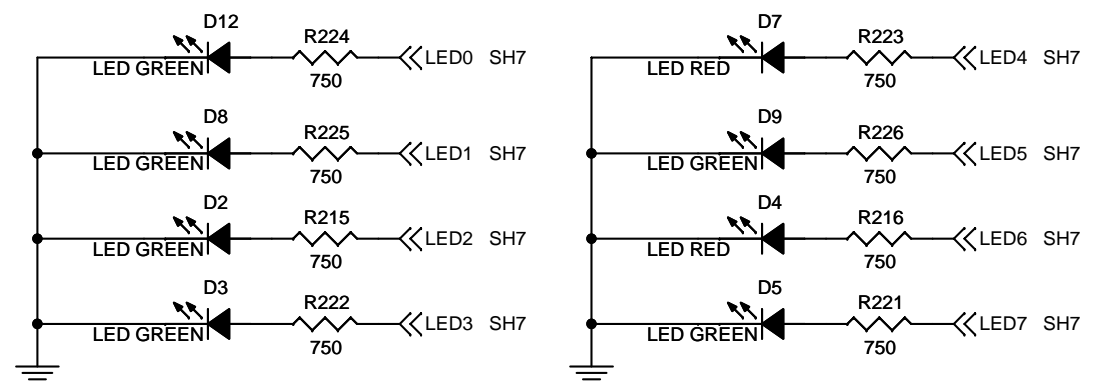
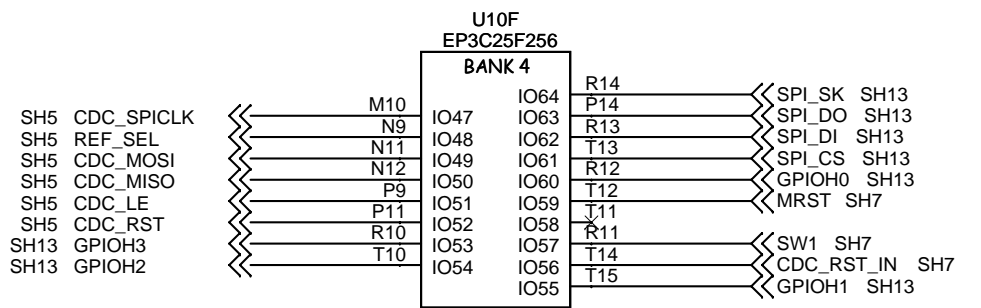
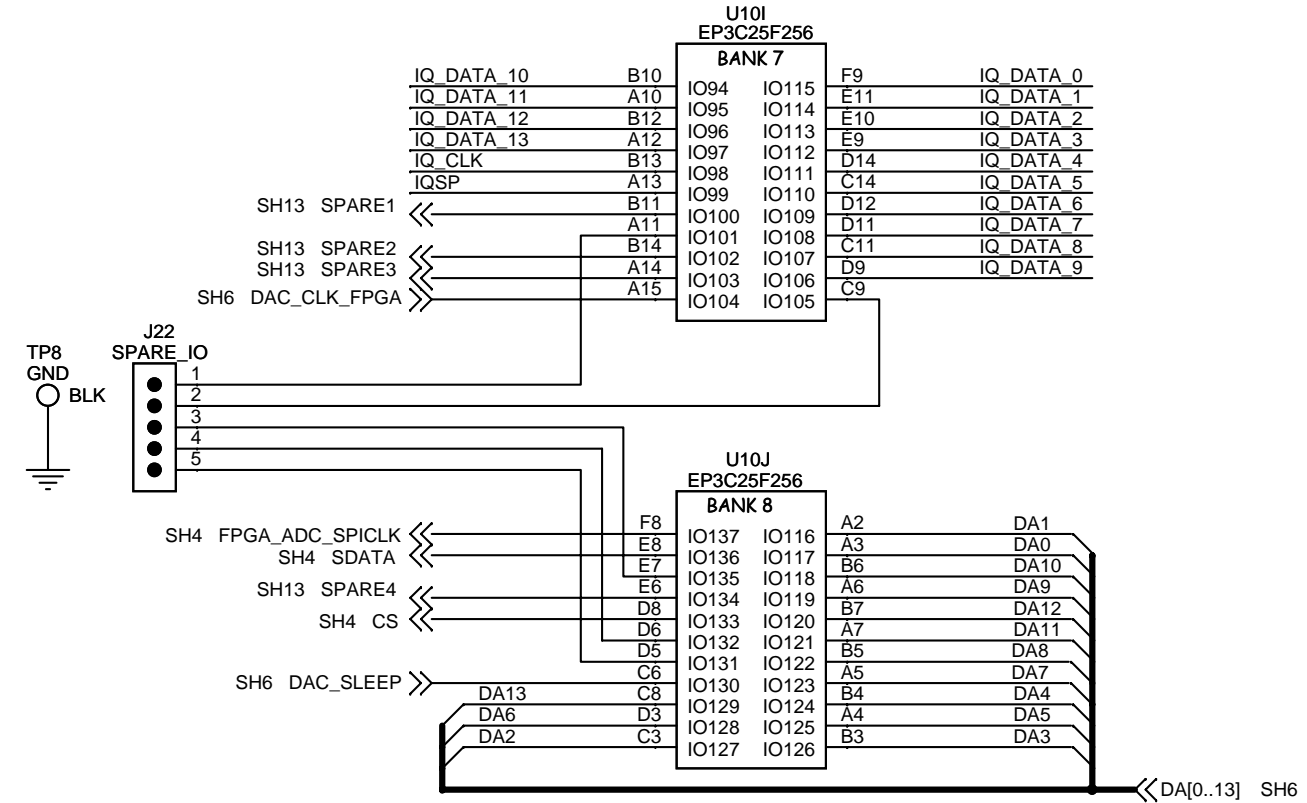
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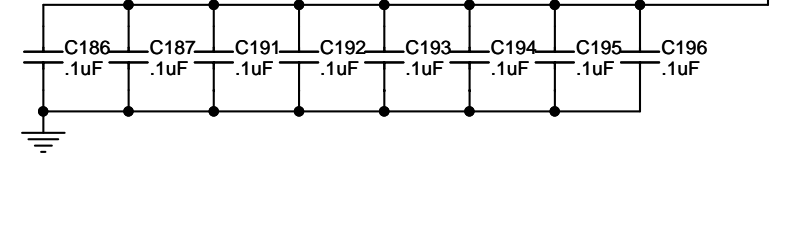
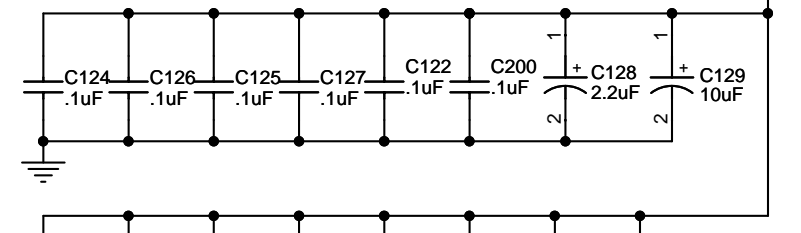
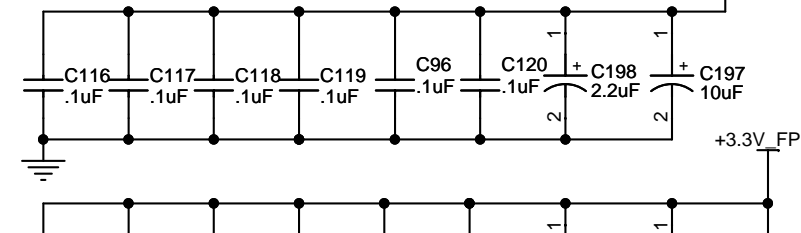
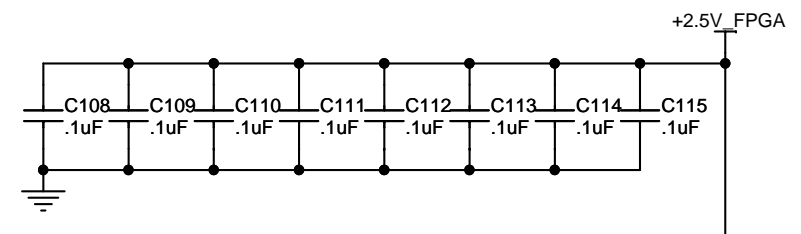
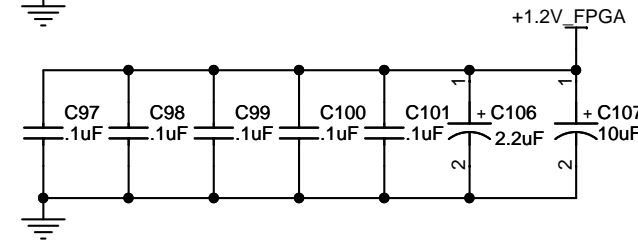
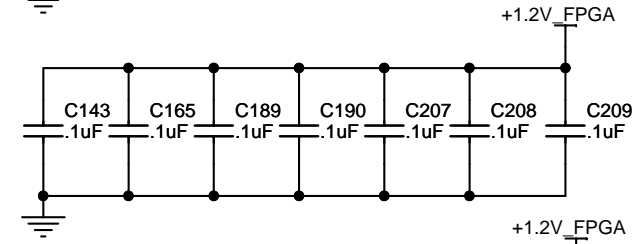
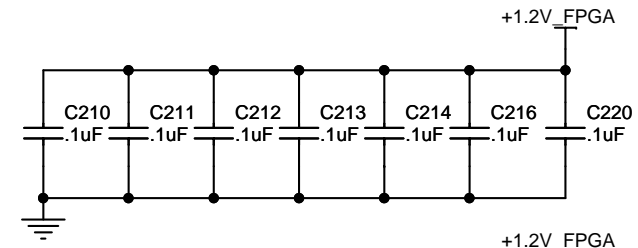
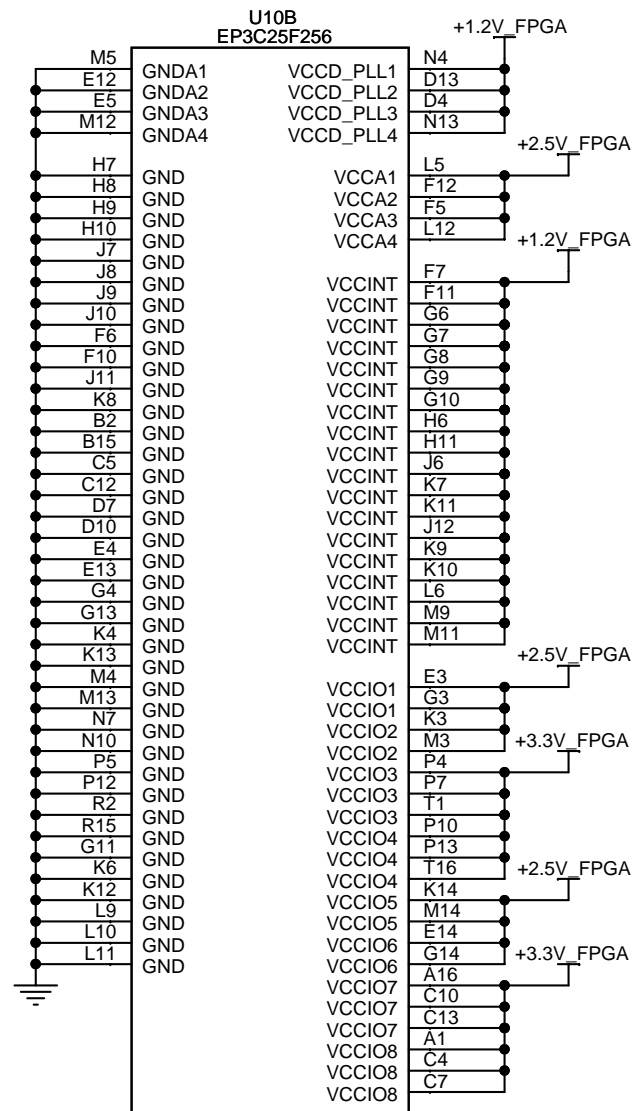
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Size	Document Number	Rev
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Title: **TSW6011 EVM**

Size: B	Document Number: FPGA I/O BANKS	Rev: C
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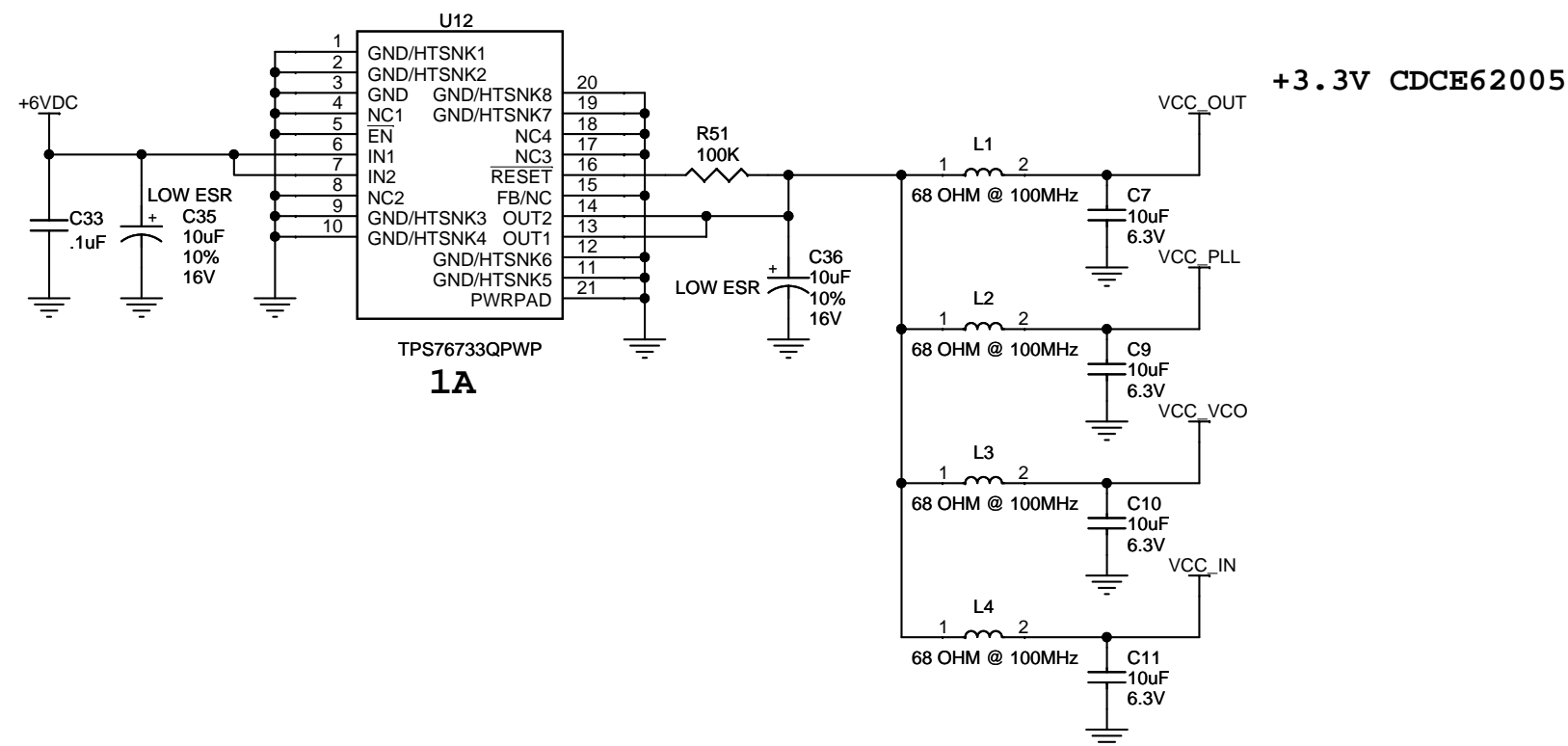
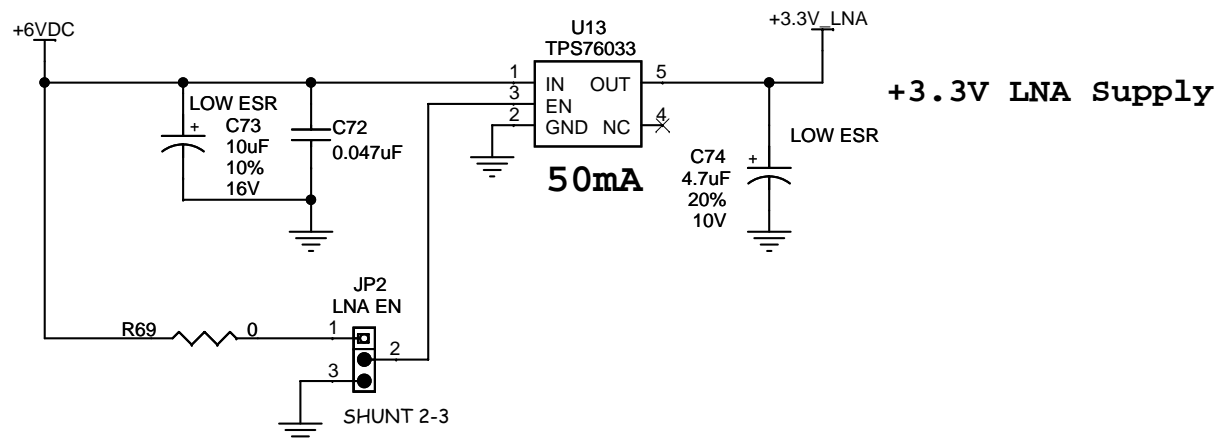
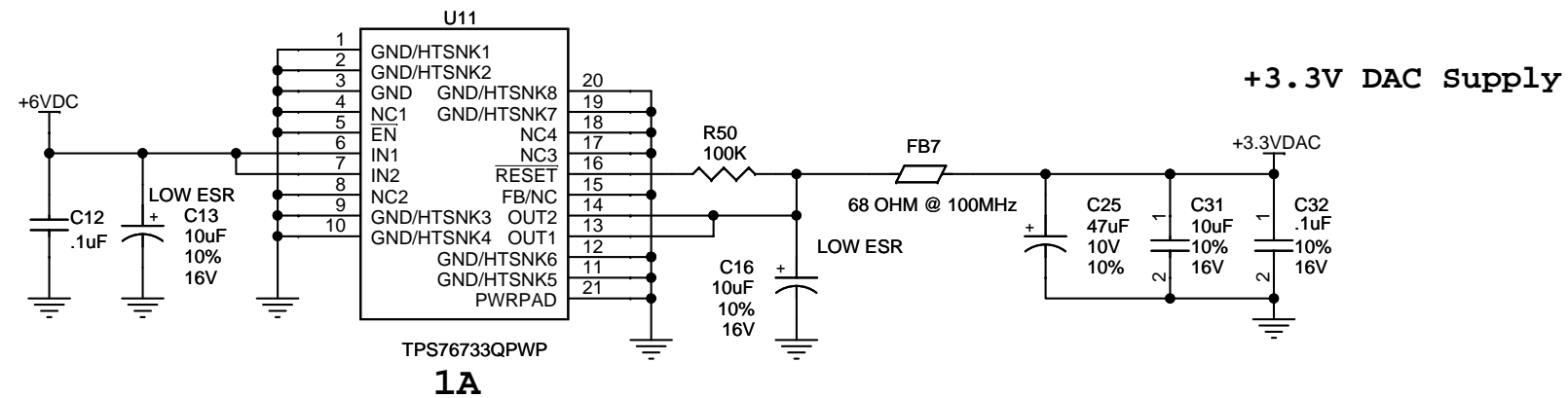
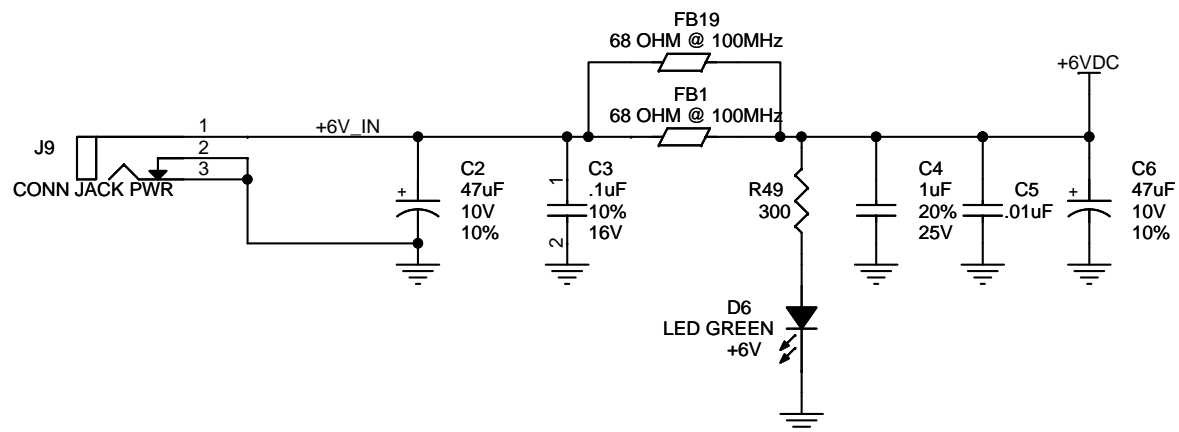


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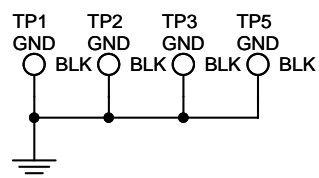
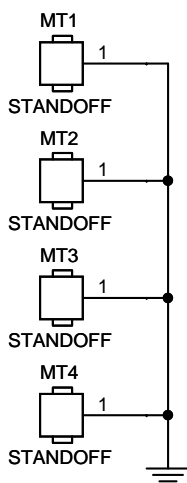
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Size: B	Document Number: FPGA Decoupling	Rev: C
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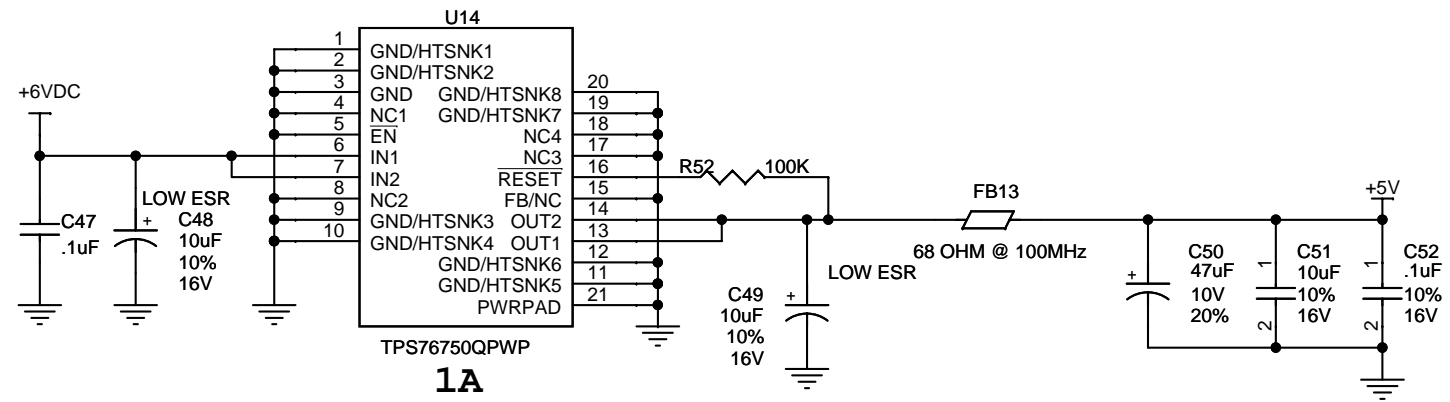
Date: Thursday, August 12, 2010 Sheet 9 of 14



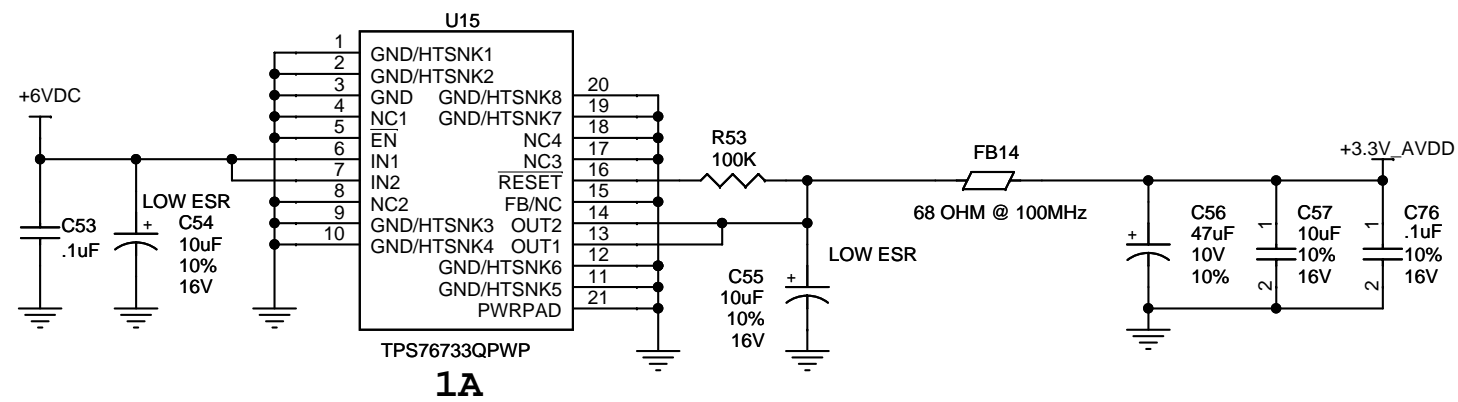
MECHANICAL PARTS
SCREWS ARE FOR THE STANDOFFS



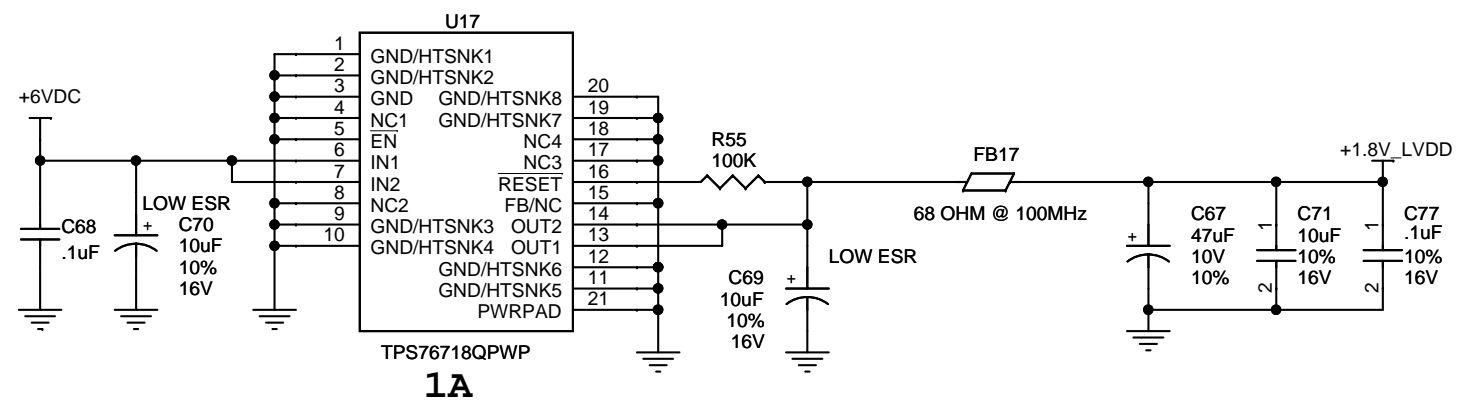
Title			TSW6011 EVM		
Size	Document Number	POWER			Rev
B					C
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TRF3711 +5V



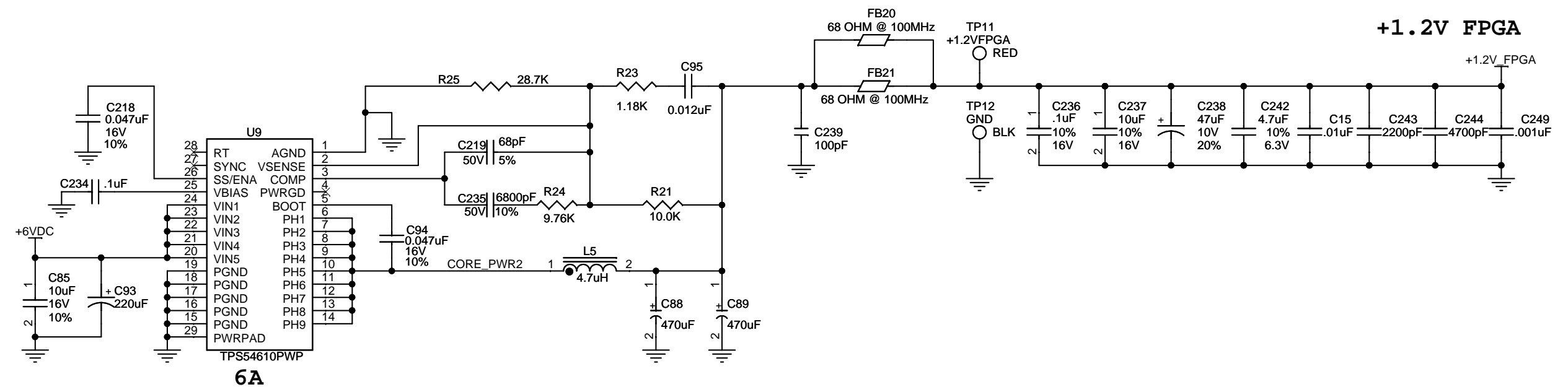
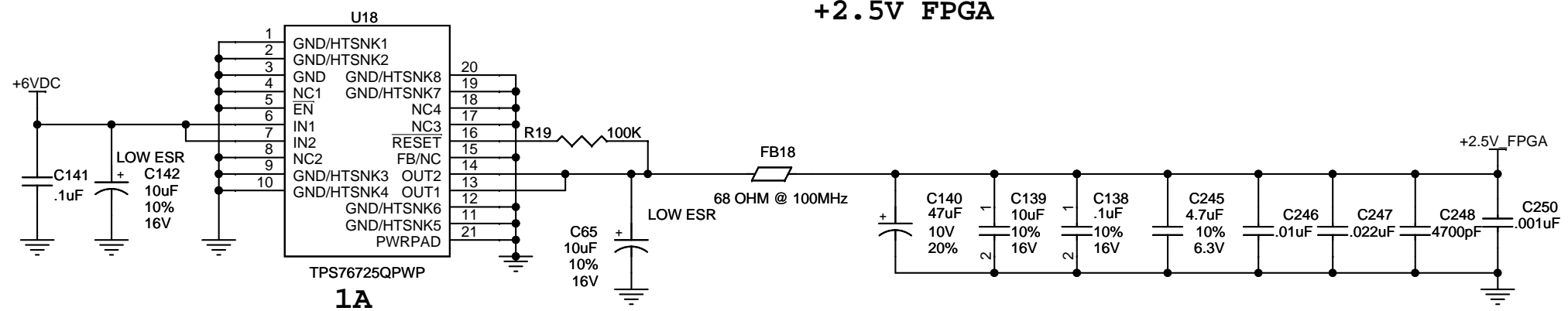
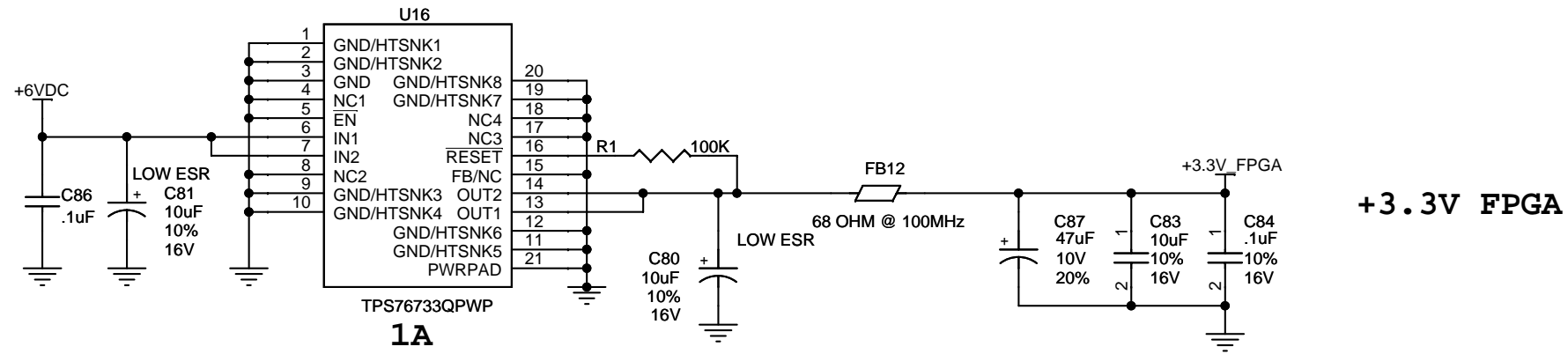
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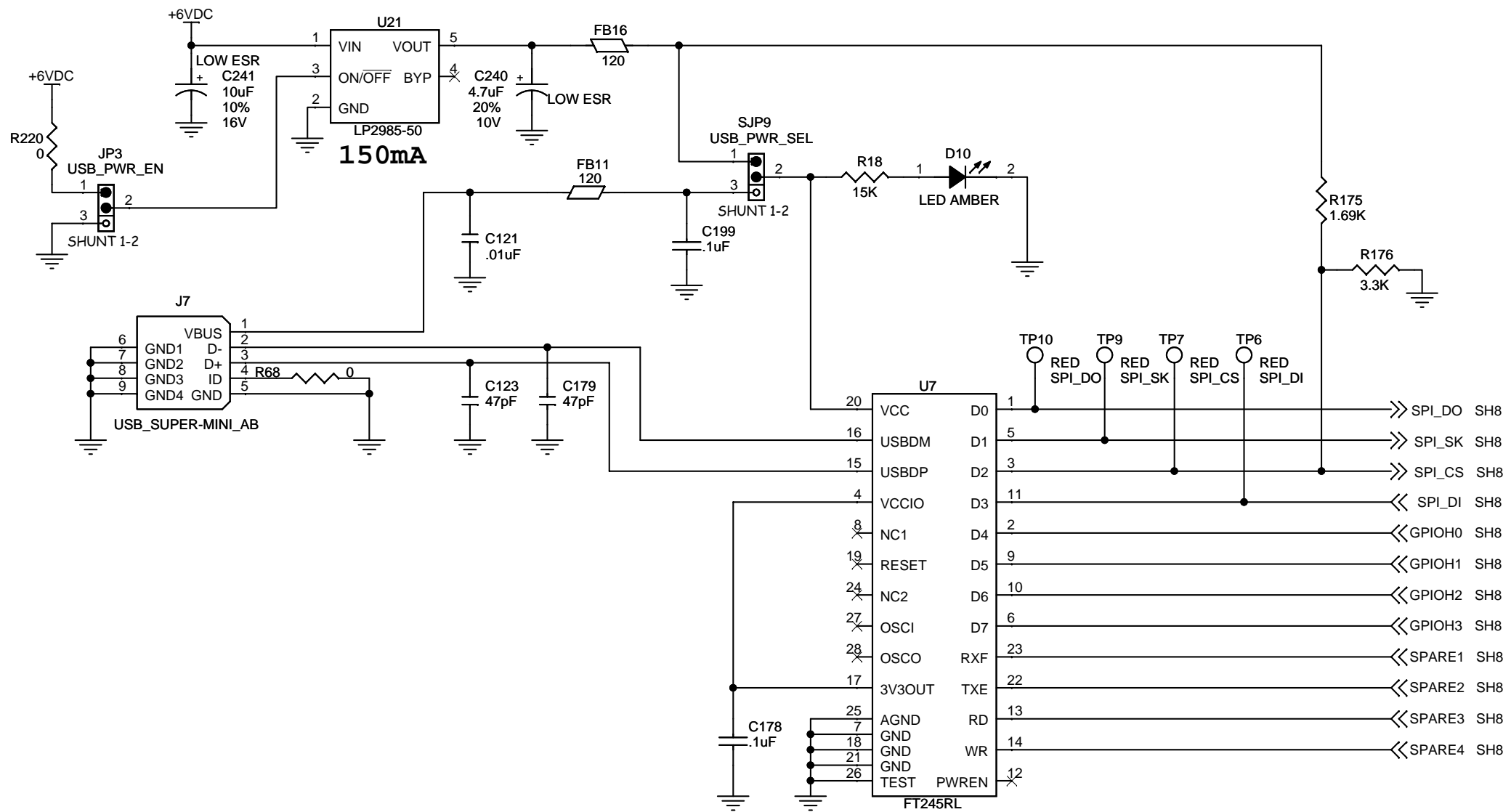
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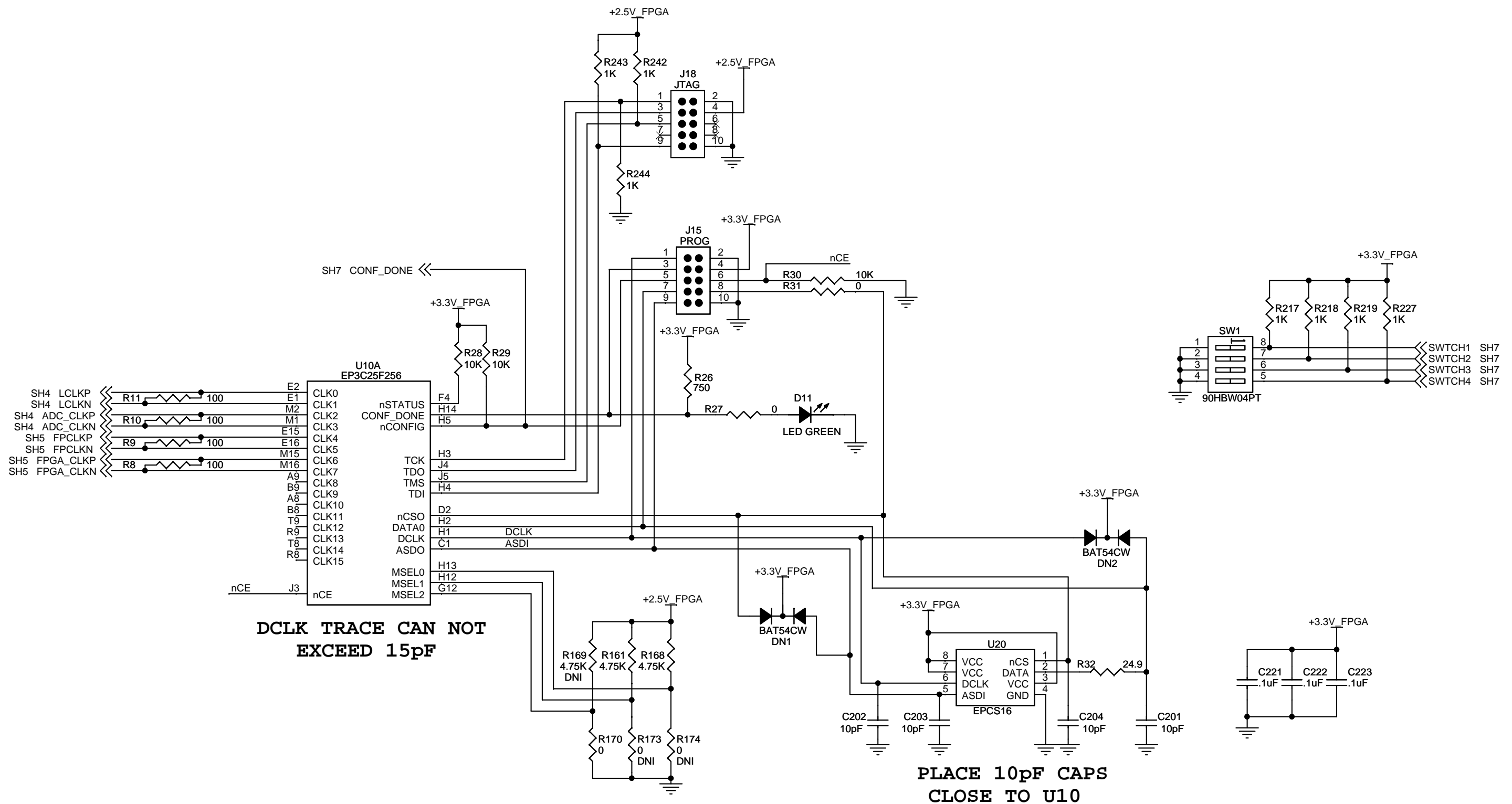
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Size	Document Number	Rev
B	POWER	C
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SERIAL INTERFACE



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DCLK TRACE CAN NOT EXCEED 15pF

PLACE 10pF CAPS CLOSE TO U10

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Title		
<i>TSW6011 EVM</i>		
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B	FPGA SPECIAL BANK & JTAGE	C
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